

MATERIAL:
 Housing: LCP, 94V-0, Black
 Contact: Copper Alloy
 Latch: Stainless Steel; 50u" Nickel Subplate; 100u" Matte Tin Overall
 Contact Plating: Specified Au thickness in Contact area; Au Flash on remaining area ;50u" min Nickel subplate

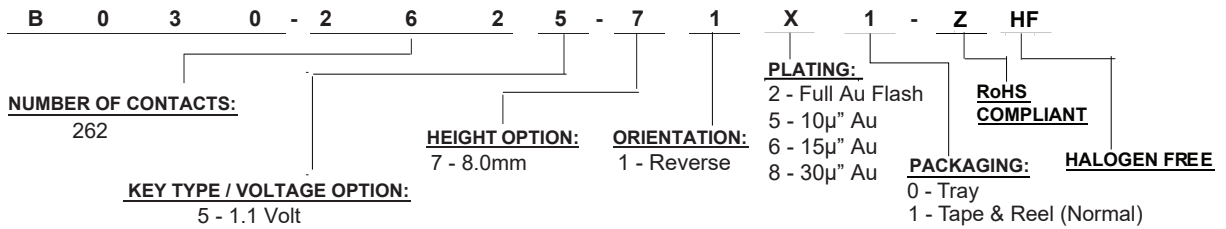
Recommended Stencil Thickness : 0.12 min.
 Reflow Compatible : 260 C max for 10 sec.

MECHANICAL:
 Insertion Force: 59.8 N max.
 Durability: 25 Cycles
 Shock: Pass EIA -364-27
 Vibration: Pass EIA -364-28

ELECTRICAL:
 Current Rating : 0.5 A
 Voltage Rating : 1.1 V
 Contact Resistance: 40 milliohms initial; 20 milliohm max change
 Insulation Resistance : 1 Megaohm min at 500V DC
 Dielectric Withstanding Voltage: 250 VAC min for 1 minute

ENVIRONMENTAL:
 Operating Temperature: -55 C to 85 C
 Solderability: Pass JESD22-B102 C
 Humidity : Pass EIA 364-21
 Thermal Shock :EIA-364-32, Method A, Table 2 Test Condition 1
 Salt Spray : 48 H

HOW TO ORDER:



Rev	Drawn	Checked	Approved	Date
0	B.S.	S.M.	S.M.	06/24/25

SMP TECHNOLOGY, INC.

DDR 5 SO DIMM Socket, 262 Position, 1.1Volt,
 Reverse Orientation, 8.0mm Height,

